

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

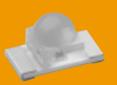








Product Guide



H_1105W Series, Dome Lens Type SMT LED

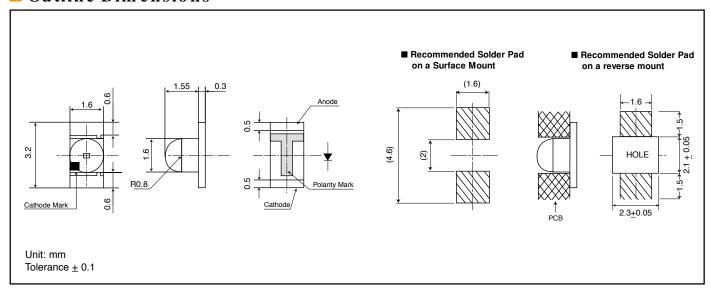
Features

- · Dome lens provides intensified narrow, bright beam
- · Available for both standard and reverse mounting
- Wider operating temperature: -40° ~ +100°C (HBG: -40° ~ +85°C)

Applications

- · High-beam indicator for automotive use
- · Backlighting for automotive dashboards
- · Indoor / outdoor full-color signboards

Outline Dimensions



Electro-Optical Characteristics

(Ta=25°C)

Part No.	Material	Emitted Color	Lens Color	Luminous Intensity _V			Wavelength Spectral Line Peak Dominant Half Width				Forward Voltage v₅			Reverse Current IR		Viewing Angle
				MIN.	TYP.	İF	λp TYP.	λd TYP.	Δλ. ΤΥΡ.	lF	TYP.	MAX.	lF	MAX.	VR	(2 θ 1/2)
HKR1105W	GaAlAs	Red		70	150	20	660	647	25	20	1.8	2.5	20	100	4	30°
HBR1105W	GaAlAs	Red		25	50	20	660	647	30	20	1.7	2.0	20	100	4	50°
HAA1105W	GaAsP	Orange		10	20	20	605	606	30	20	2.2	2.5	20	100	4	
HAY1105W	GaAsP	Yellow	Water	10	20	20	580	590	30	20	2.2	2.5	20	100	4	
HPY1105W	GaP	Yellow-Green	Clear	20	50	20	570	572	30	20	2.1	2.5	20	100	4	40°
HPG1105W	GaP	Green		15	30	20	560	567	30	20	2.1	2.5	20	100	4] ~~
HBG1105W	GaP	Pure Green		6	12	20	555	558	30	20	2.1	2.5	20	100	4	
	Units				mcd n		nm			mA	V mA		μΑ	٧	Deg.	

■ Absolute Maximum Ratings

(Ta=25°C)

Item		Red	Orange	Yellow	Yellow-Green	Green	Pure Green	Units
Item	Symbol	HBR, HKR	HAA	HAY	HPY	HPG	HBG	
Power Dissipation	Pd	60(HBR),75(HKR)	75	75	75	75	75	mW
Forward Current	I _F	30	30	30	30	30	30	mA
Peak Forward Current	I FM	70	70	70	70	70	70	mA
Reverse Voltage	VR	4	4	4	4	4	4	V
Operating Temperature	Topr		-40 to +85	°C				
Storage Temperature	Tstg		-40 to +100	°C				
Derating*	ΔIF		0.42 (DC) 0.93 (Pulse)	mA/°C				

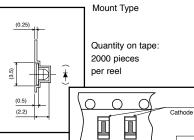
^{*} Ta=25°C, I_{FM} applies for the pulse width ≤ 1msec. and duty cycle ≤1/20.

The current derating for operation applies when the temperature is above 25°C for HBG and 75°C for HVR, HBR, HKR, HAA, HAY, HPY & HPG

Direction to pull

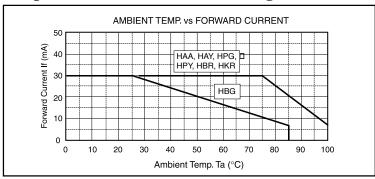
Taping Specifications

2+0.05

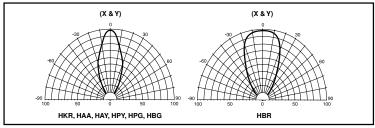


for Reverse

Operation Current Derating Chart (DC)



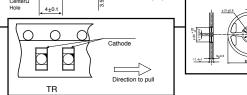
Spatial Distribution



Taping Specifications for

for Standard Mount Type

Quantity on tape: 2000 pieces per reel



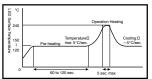
Precautions

(1.85)

Please follow these handling precautions to prevent damage to the chip and ensure its reliability.

1. Soldering conditions:

- <u>Soldering iron</u>: Temperature at tip of iron: 280°C max. (30W max.) Soldering time: 3 sec. max.
- <u>Dip soldering</u>: Preheating: 120 ~ 150°C max. (resin surface temp.)
 60 ~ 120 sec. max. Bath temperature: 260°C max. Dipping Time: 5 sec. max.
- · Reflow Soldering:



2. Cleaning:

- If cleaning is required, use the following solutions for less than 1 minute, at less than 40°C.
- Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Product specifications subject to change without notice. PGH__1105W-0301

